22299-1(61-649)

DECLARATION OF INVENTORSHIP AND POWER OF ATTORNEY FOR PATENT APPLICATION

👼 a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

SEMICONDUCTOR PACKAGE HAVING CONDUCTIVE BUMPS ON CHIP AND METHOD FOR FABRICATING THE SAME

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tion of which	·		
under Applica	ation Serial No	and	was
		(if applicable)	
laims, as amended by an the duty to disclose to CFR § 1.56. foreign priority benefits ificate listed below and	y amendment referred to ab the Office all information under 35 USC § 119 of an have also identified below	ove. which is material to Patentability y foreign application(s) for pate any foreign application for pate	ty as
Application(s)			
ATION NUMBER 2115508	<u>COUNTRY</u> TAIWAN, R.O.C.	FILING DATE June 09, 2003	
	is attached he was filed on under Applica amended on that I have reviewed and laims, as amended by an the duty to disclose to CFR § 1.56. foreign priority benefits ificate listed below and ficate having a filing dat Application(s) ATION NUMBER	is attached hereto. was filed on under Application Serial No. amended on that I have reviewed and understand the contents of laims, as amended by any amendment referred to about the duty to disclose to the Office all information CFR § 1.56. foreign priority benefits under 35 USC § 119 of an inficate listed below and have also identified below ficate having a filing date before that of the application(s) ATION NUMBER COUNTRY	is attached hereto. was filed on under Application Serial No. amended on (if applicable) that I have reviewed and understand the contents of the above-identified specifical laims, as amended by any amendment referred to above. the duty to disclose to the Office all information which is material to Patentability EFR § 1.56. foreign priority benefits under 35 USC § 119 of any foreign application(s) for paterificate listed below and have also identified below any foreign application for paterificate having a filing date before that of the application on which priority is claimed Application(s) ATION NUMBER COUNTRY FILING DATE

I hereby claim the benefit under 35 USC §120 of any United States application(s) listed below and insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of 35 USC § 112, I acknowledge the duty to disclose to the Office information which is material to patentability as defined in CFR § 1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application.

APPLICATION NUMBER FILING DATE STATUS
(Patented, Pending, Abandoned)

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

Address all correspondence to: Mr. Steven M. Jensen

Mr. Peter F. Corless

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101 Federal Street, Boston, MA 02110,

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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 USC 1001, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Full name of sole or first inventor	
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Inventor's Signature	Date
Residence	Citizenship
Post Office Address	